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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of

Applicant Young-Joon Park, et al.

Docket Number: TI-35623

Serial No.: 10/628,198

Art Unit: 2814

Filed: 07/28/03

Examiner: Ginette Peralta

For: A Two Step Semiconductor Manufacturing Process for
Copper Interconnects

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NAME OF INVENTOR(S): Young-Joon Park, et al.	
TITLE OF INVENTION: A Two Step Semiconductor Manufacturing Process for Copper Interconnects	
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Texas Instruments Incorporated
PO Box 655474, M/S 3999
Dallas, TX 75265-5474